



Product Change Notification

110682 - 02

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #: 110682 - 02
Change Title: Intel® Desktop Board DP67BGB3, Boxed and Bulk
PCN 110682-02, Product Design
Update to DP67BGB3 Printed Circuit Board to Improve Functionality and Performance
Reason for Revision: Change to Pre-Change AA#
Date of Publication: September 26, 2011

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	Nov 14, 2011
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Description of Change to the Customer:

Reason for Revision: Change to Pre-Change AA#

The printed circuit board for DP67BGB3 will be updated to improve functionality and performance.

Updates include:

1. The LAN circuit will have some component changes to enhance functionality.
2. A trace within the Audio circuitry will be moved to enhance signal quality.
3. The KC Registration label will be replaced by a silkscreen version on the PCB.
4. Hardware support added for future processors.
5. The alternate power LED header traces will be fixed to enable operation.
6. The previous changes to the on board power supply circuitry for improved voltage and timing margins will be enhanced.

Specific component changes:

1. R1375 will change from 47K to 10K ohm.
2. C1157 will change from 10uF to 1uF.
3. A 2.2uF cap will be added at C137 (already 1000PF).
4. C162~C193 and C980~C995 will change from 0.1uF to 0.22uF
5. 0 ohm resistors will be added at R1557 and R1558
6. The PCIe x16 slot AC decoupling capacitor values will change from 100nF to 220nF. The capacitor location designators are from XC1 to XC32.

7. CPU pins will be connected to on-board voltage regulator resistor divider

Customer Impact of Change and Recommended Action:

The Printed Circuit board is being replaced with a new version where a couple of traces have been moved and the Korean Certification mark is being added directly to the silkscreen.

This change has been thoroughly evaluated to ensure that there are no quality, reliability or functional implications to our customers. Intel is not recommending additional qualification of these changes on platforms received from Intel.

Intel will attempt to deplete pre-conversion material before shipping post-conversion material but there is a possibility of Intel shipping mixed inventory. Therefore, customers will need to manage and migrate to the post-conversion material as soon as possible.

Milestone dates are estimates and subject to change based on business and operational conditions.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change AA	Post Change AA
BOXDP67BGB3	915077	G10491-307	G10491-400
BLKDP67BGB3	915078	G10491-307	G10491-400

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
May 25, 2011	00	Originally Published PCN
August 2, 2011	01	Revise milestone date.
September 26, 2011	02	Change to Pre-Change AA#